

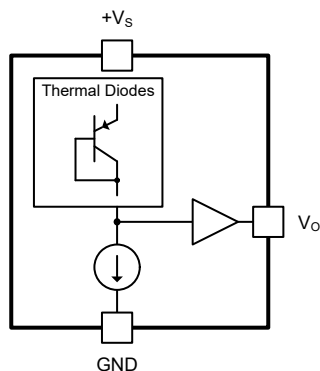
## LM60 2.7V、SOT-23 または TO-92 温度センサ

### 1 特長

- 業界標準のセンサのゲイン / オフセット:
  - 6.25mV/°C、0°C で 424mV
- LM60B の温度精度:
  - 25°C で ±2°C (最大値)
  - -25°C ~ +125°C (レガシー チップ) および -40°C ~ +125°C (新チップ) の範囲で ±3°C (最大値)
- LM60C の温度精度:
  - 25°C で ±3°C (最大)
  - -40°C ~ +125°C の範囲で ±4°C (最大値)
- 広い電源電圧範囲: 2.7V ~ 10V
- 25°C での静止電流 110µA (最大値 / レガシー チップ) および 70µA (最大値 / 新チップ)
- パッケージ オプション:
  - SOT-23 (3 ピン)
  - TO-92 (3 ピン、ストレートリード)
  - TO-92 (3 ピン、成形リード)
- 非線形性: ±0.8°C (最大値)
- DC 出力インピーダンス: 120Ω / 800Ω (標準値 / 最大値)
- リモート アプリケーションに最適

### 2 アプリケーション

- 携帯電話、PC およびノート PC
- 電源モジュール
- バッテリー管理
- 家庭用プリンタおよび複合機 (マルチファンクション プリンタ)
- HVAC およびソリッド ステートドライブ
- 電化製品



概略回路図

### 3 概要

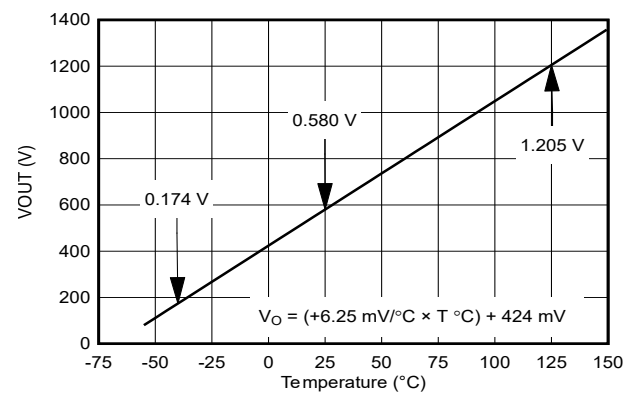
LM60 デバイスは高精度の統合回路温度センサです。2.7V ~ 10V の単一電源で動作し、-40°C ~ +125°C の温度範囲を検出できます。デバイスの出力電圧は摂氏温度に直線的に比例 (6.25mV/°C) し、DC オフセットは 424mV です。このオフセットにより、負電源を必要とせずに負温度を読み取ることができます。デバイスの公称出力電圧は、-40°C ~ +125°C の温度範囲で 174mV ~ 1205mV です。このデバイスは、室温で ±2°C、-25°C ~ +125°C (レガシー チップの場合) または -40°C ~ +125°C (新チップの場合) の全温度範囲で ±3°C の精度を維持するよう較正されています。

デバイスの線形出力、424mV のオフセット、工場での較正により、単一電源の環境で負温度の読み取りが要求される場合に必要なる外部回路が簡素化されます。デバイスの静止電流は 110µA 未満 (レガシー チップの場合)、70µA 未満 (新チップの場合) なので、自己発熱は、SOT-23 パッケージの静止空气中で非常に低い 0.1°C に制限されます。このデバイスは本質的に低消費電力であり、様々な論理ゲートの出力から直接電源を供給できるので、専用の制御端子を備えていなくても容易にシャットダウンができます。

#### パッケージ情報

部品番号	パッケージ <sup>(1)</sup>	パッケージ サイズ <sup>(2)</sup>
LM60	LP (TO-92, 3)	4.83mm × 7.37mm
	DBZ (SOT-23, 3)	2.37mm × 2.92mm

- 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。
- パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



全範囲の摂氏温度センサ  
(-40°C ~ +125°C)



## Table of Contents

<b>1 特長</b> .....	<b>1</b>	<b>8 Application and Implementation</b> .....	<b>11</b>
<b>2 アプリケーション</b> .....	<b>1</b>	8.1 Application Information.....	11
<b>3 概要</b> .....	<b>1</b>	8.2 Typical Applications.....	12
<b>4 Device Comparison</b> .....	<b>3</b>	8.3 System Examples.....	14
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	8.4 Power Supply Recommendations.....	14
<b>6 Specifications</b> .....	<b>4</b>	8.5 Layout.....	14
6.1 Absolute Maximum Ratings.....	4	<b>9 Device and Documentation Support</b> .....	<b>17</b>
6.2 ESD Ratings.....	4	9.1 Documentation Support.....	17
6.3 Recommended Operating Conditions.....	4	9.2 ドキュメントの更新通知を受け取る方法.....	17
6.4 Thermal Information.....	4	9.3 サポート・リソース.....	17
6.5 Electrical Characteristics.....	5	9.4 Trademarks.....	17
6.6 Typical Characteristics.....	6	9.5 静電気放電に関する注意事項.....	17
<b>7 Detailed Description</b> .....	<b>10</b>	9.6 用語集.....	17
7.1 Overview.....	10	<b>10 Revision History</b> .....	<b>17</b>
7.2 Functional Block Diagram.....	10	<b>11 Mechanical, Packaging, and Orderable Information</b> .....	<b>18</b>
7.3 Feature Description.....	10		
7.4 Device Functional Modes.....	10		

## 4 Device Comparison

表 4-1. Device Comparison

ORDER NUMBER	PACKAGE	ACCURACY OVER TEMPERATURE	SPECIFIED TEMPERATURE RANGE
LM60BIM3X/NOPB	SOT-23 (DBZ) 3-pin	$\pm 3^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60CIM3X/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)
LM60QIM3X/NOPB		$\pm 4^{\circ}\text{C}$	$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
LM60BIZ/LFT3	TO-92 (LP) 3-pin Formed Leads	$\pm 3^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60BIZ/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)
LM60CIZ/NOPB	TO-92 (LP) 3-pin Straight Leads	$\pm 4^{\circ}\text{C}$	$-25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}^{(1)}$ (Legacy chip)
LM60CIZ/NOPB			$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ (New chip)

(1) LM60B (Legacy chip) operates down to  $-40^{\circ}\text{C}$  without damage but the accuracy is only verified from  $-25^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

表 4-2. Device Nomenclature

PRODUCT	OUT
LM60xlyyy/NOPB LM60xlyyy/LFT3	<p><b>x</b> indicates that the device has <b>B</b>, <b>C</b> or <b>Q</b> (grade-1 device in accordance with the AEC-Q100 standard) variant. These devices can ship with the legacy chip (CSO: GF6 or SHE) or the new chip (CSO: RFB) with different <i>date code</i>. The reel packaging label provides date code information to distinguish which chip is being used. Device performance for new and legacy chips is denoted throughout the document.</p> <p><b>yyy</b> indicates that the package type of the device which can be <b>M3X/NOPB</b> (SOT-23 3-pin) or <b>Z/LFT3</b> (TO-92 3-pin Formed Leads) or <b>Z/NOPB</b> (TO-92 3-pin Straight Leads).</p> <p>For more information on TO-92 package options please see: <a href="#">TO-92 Packing Options / Ordering Instructions</a></p>

## 5 Pin Configuration and Functions

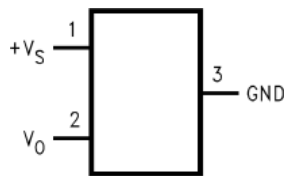


図 5-1. DBZ Package  
3-Pin SOT-23  
Top View

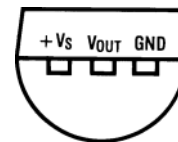


図 5-2. LP Package  
3-Pin TO-92  
(Formed Leads and Straight Leads)  
Bottom View

表 5-1. Pin Functions

NAME	PIN		TYPE	DESCRIPTION
	SOT-23	TO-92		
GND	3	3	GND	Device ground, connected to power supply negative terminal
V <sub>OUT</sub>	2	2	O	Temperature sensor analog output
+V <sub>S</sub>	1	1	POWER	Positive power supply pin

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating free-air temperature range unless otherwise noted<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage, +V <sub>S</sub>	LM60	-0.2	12	V
Output voltage, V <sub>O</sub>		-0.6	+V <sub>S</sub> + 0.6	V
Output current, I <sub>OUT</sub>			10	mA
Input current at any pin <sup>(2)</sup>			5	mA
Maximum junction temperature, T <sub>JMAX</sub>			125	°C
Storage temperature, T <sub>stg</sub>		-65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) When the input voltage (V<sub>I</sub>) at any pin exceeds power supplies (V<sub>I</sub> < GND or V<sub>I</sub> > +V<sub>S</sub>), the current at that pin must be limited to 5mA.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub> , Electrostatic discharge	LM60 (DBZ Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	
	LM60 (LP Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2500	
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT	
+V <sub>S</sub>	Supply voltage	LM60	2.7	10	V	
T <sub>A</sub> , (T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> )	Specified temperature	LM60B	Legacy chip	-25 <sup>(2)</sup>	125	°C
		LM60B	New chip	-40	125	°C
		LM60C		-40	125	°C

- (1) Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to www.national.com/packaging. Reflow temperature profiles are different for lead-free and non-lead-free packages.
- (2) LM60B (Legacy chip) operates down to -40°C without damage but the accuracy is only ensured from -25°C to 125°C.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LM60				UNIT
		DBZ (SOT-23) 3 PINS		LP (TO-92) 3 PINS		
		Legacy chip	New chip	Legacy chip	New chip	
R <sub>θJA</sub> <sup>(2)</sup>	Junction-to-ambient thermal resistance	266	240.6	162	135.9	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	135	144.5	85	109.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	59	72.3	-	108.9	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	18	28.7	29	24.6	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	58	71.7	142	108.9	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

(2) The junction to ambient thermal resistance ( $R_{\theta JA}$ ) is specified without a heat sink in still air.

## 6.5 Electrical Characteristics

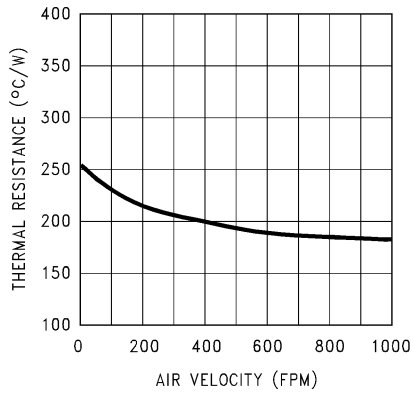
Unless otherwise noted, these specifications apply for  $+V_S = 3V$  (DC) and  $I_{LOAD} = 1\mu A$ . All limits  $T_A = T_J = 25^\circ C$  unless otherwise noted.

PARAMETER		TEST CONDITIONS		MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT	
<b>SENSOR ACCURACY</b>								
$T_{ACY}$	Temperature accuracy <sup>(3)</sup>	LM60B <sup>(4)</sup>		-2		2	°C	
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-3		3		
		LM60C		-3		3		
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-4		4		
<b>SENSOR OUTPUT</b>								
$V_{0^\circ C}$	Output voltage offset at 0°C				424		mV	
$T_C$	Temperature coefficient (sensor gain)				6.25		mV/°C	
		LM60B	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	6.06		6.44		
		LM60C	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	6		6.5		
$V_{ONL}$	Output Nonlinearity <sup>(5)</sup>	LM60B	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.6		0.6	°C	
		LM60C	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.8		0.8		
$Z_{OUT}$	Output impedance					800	$\Omega$	
$T_{LTD}$	Long-term stability and drift <sup>(6)</sup>	$T_J = T_{MAX} = 125^\circ C$ for 1000 hours			$\pm 0.2$		°C	
<b>POWER SUPPLY</b>								
$I_{DD}$	Operating current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip		82	110	$\mu A$	
			New chip		52	70		
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	Legacy chip				125
			$T_A = T_J = T_{MIN}$ to $T_{MAX}$	New chip				90
PSR	Line regulation <sup>(7)</sup>	LM60, $2.7V \leq +V_S \leq 3.3V$	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-2.3		2.3	mV	
		LM60, $3V \leq +V_S \leq 10V$	$T_A = T_J = T_{MIN}$ to $T_{MAX}$	-0.3		0.3	mV/V	
$\Delta I_{DD}$	Change of quiescent current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip		$\pm 5$		$\mu A$	
			New chip		$\pm 6.5$			
$I_{DD\_TEM P}$	Temperature coefficient of quiescent current				0.2		$\mu A/^\circ C$	

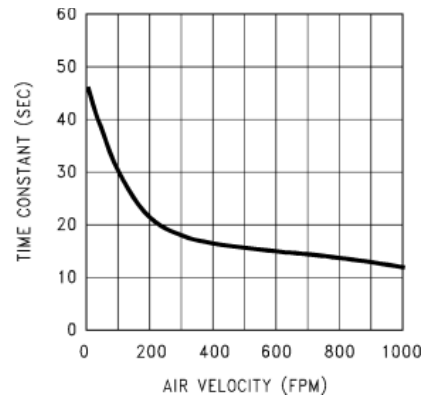
- Limits are specified to TI's AOQL (Average Outgoing Quality Level).
- Typicals are at  $T_J = T_A = 25^\circ C$  and represent most likely parametric norm.
- Accuracy is defined as the error between the output voltage and 6.25mV/°C times the case temperature of the device plus 424mV, at specified conditions of voltage, current, and temperature (expressed in °C).
- LM60B (Legacy chip) operates down to  $-40^\circ C$  without damage but the accuracy is only verified from  $-25^\circ C$  to  $125^\circ C$ . However, LM60B (New chip) specs are verified from  $-40^\circ C$  to  $125^\circ C$ .
- Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature rating of the device
- For best long-term stability, any precision circuit provides the best results if the unit is aged at a warm temperature, temperature cycled for at least 46 hours before long-term life test begins for both temperatures. This is especially true when a small (surface-mount) part is wave soldered; allow time for stress relaxation to occur. The majority of the drift will occur in the first 1000 hours at elevated temperatures. The drift after 1000 hours will not continue at the first 1000 hour rate.
- Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance

## 6.6 Typical Characteristics

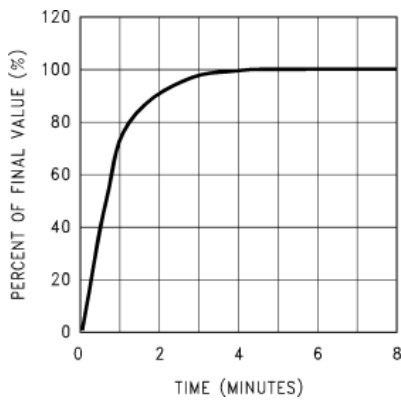
To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).



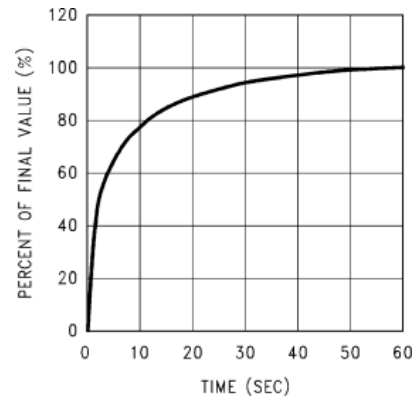
**Figure 6-1. Thermal Resistance Junction to Air (Legacy chip)**



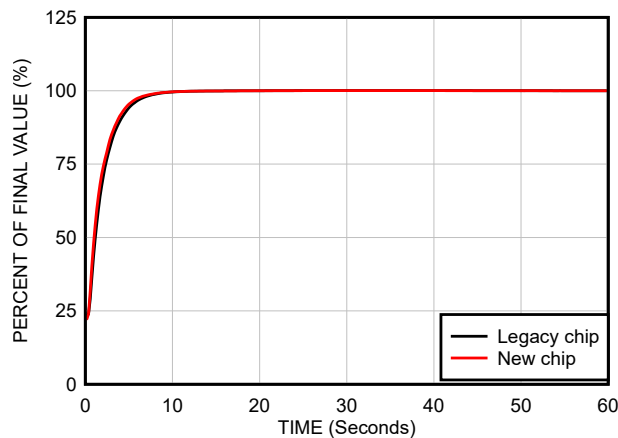
**Figure 6-2. Thermal Time Constant (Legacy chip)**



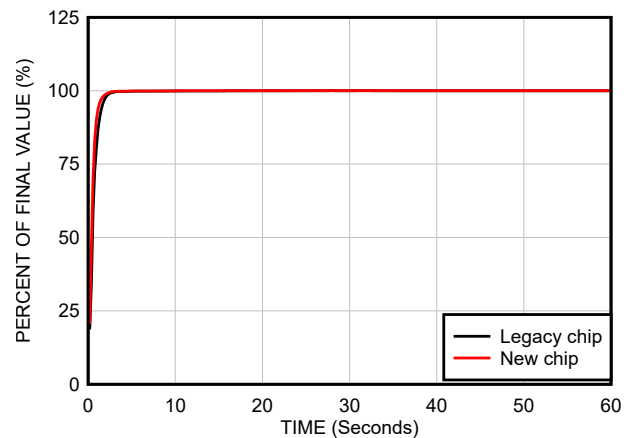
**Figure 6-3. Thermal Response in Still Air With Heat Sink (Legacy chip)**



**Figure 6-4. Thermal Response in Stirred Oil Bath With Heat Sink (Legacy chip)**



**Figure 6-5. Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches x 0.5 inches PCB board)**



**Figure 6-6. Thermal Response in Stirred Oil Bath Without Heat Sink**

## 6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).

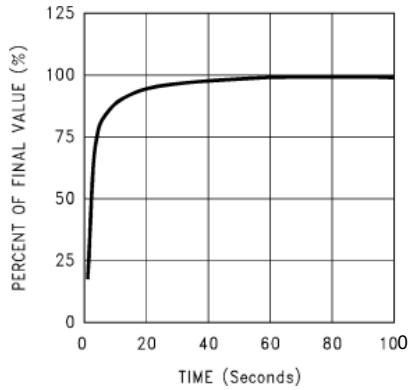


Figure 6-7. Thermal Response in Still Air Without a Heat Sink (Legacy chip)

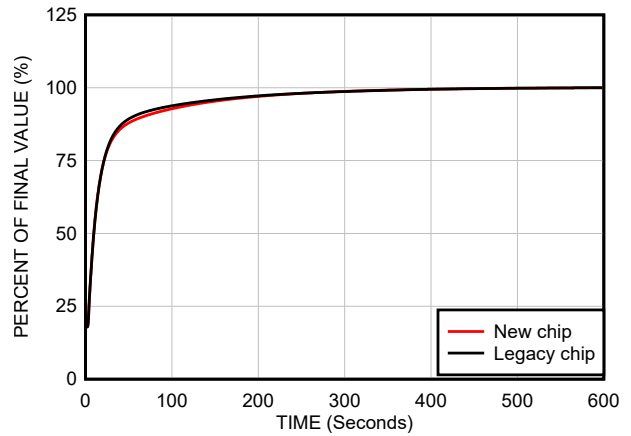


Figure 6-8. Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip in the new test setup)

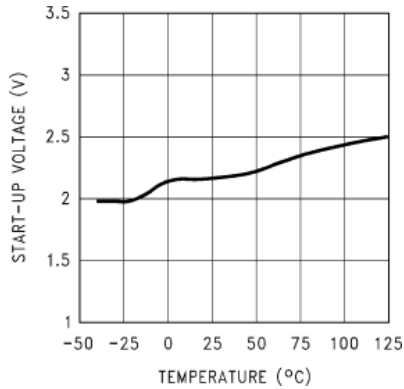


Figure 6-9. Start-Up Voltage vs Temperature (Legacy chip)

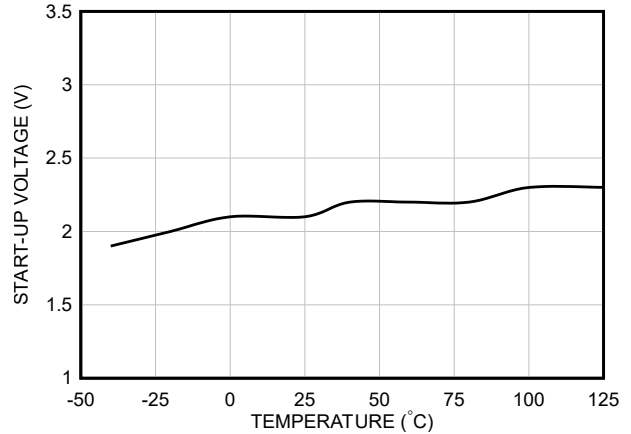


Figure 6-10. Start-Up Voltage vs Temperature (New chip)

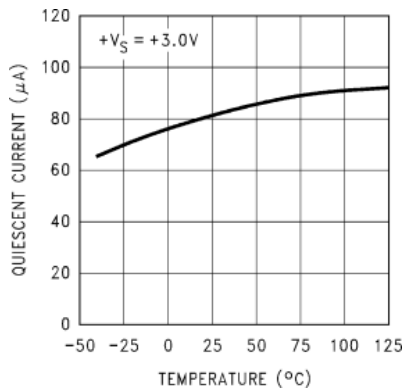


Figure 6-11. Quiescent Current vs Temperature (Legacy chip)

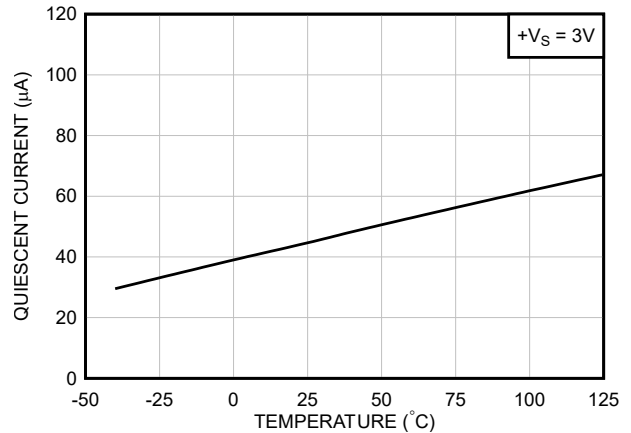
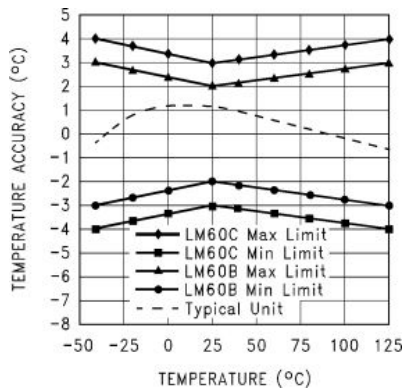


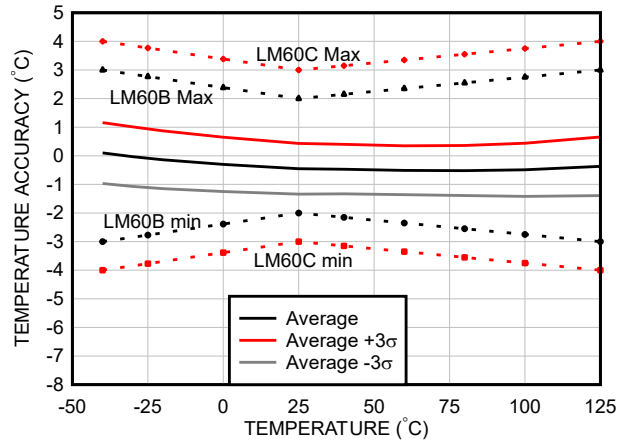
Figure 6-12. Quiescent Current vs Temperature (New chip)

### 6.6 Typical Characteristics (continued)

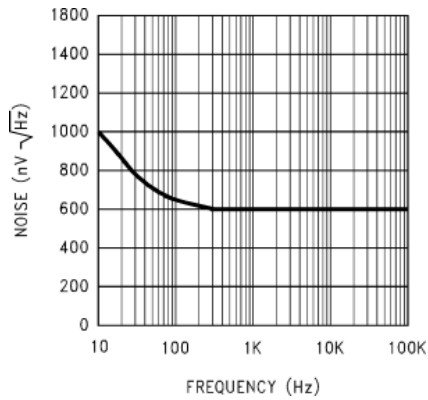
To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).



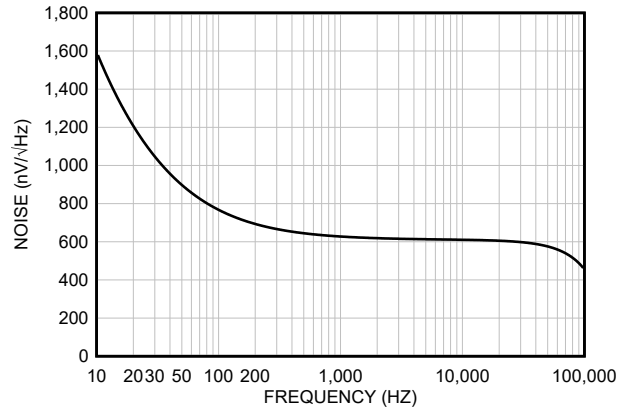
**Figure 6-13. Accuracy vs Temperature (Legacy chip)**



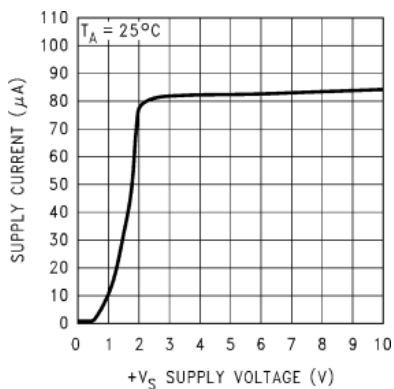
**Figure 6-14. Accuracy vs Temperature (New chip)**



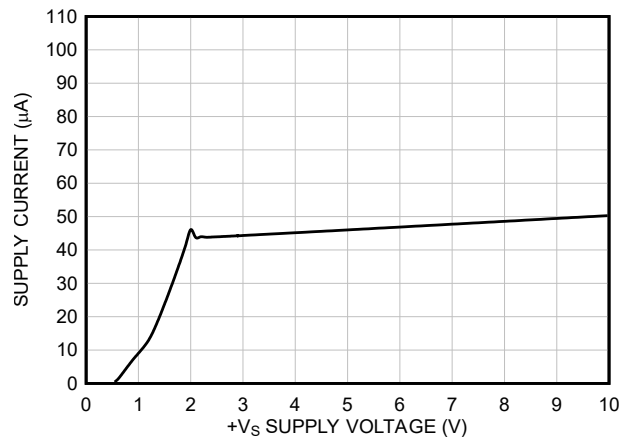
**Figure 6-15. Noise Voltage (Legacy chip)**



**Figure 6-16. Noise Voltage (New chip)**



**Figure 6-17. Supply Current vs Supply Voltage (Legacy chip)**

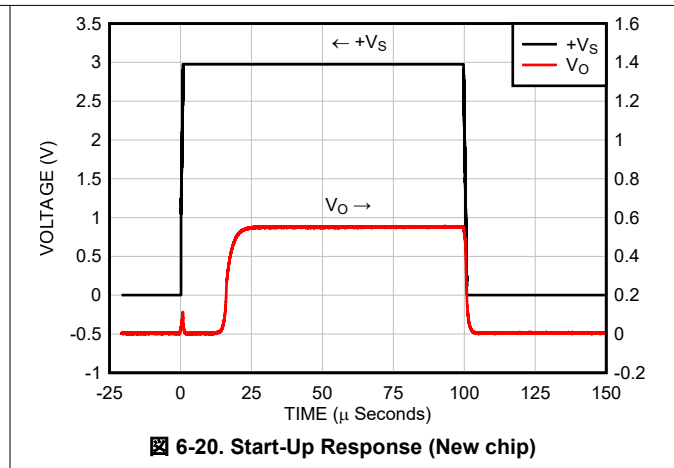
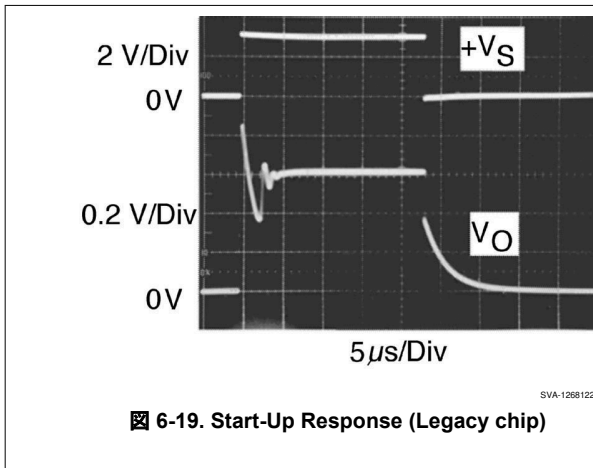


**Figure 6-18. Supply Current vs Supply Voltage (New chip)**



## 6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [Figure 8-9](#) or [Figure 8-10](#).



## 7 Detailed Description

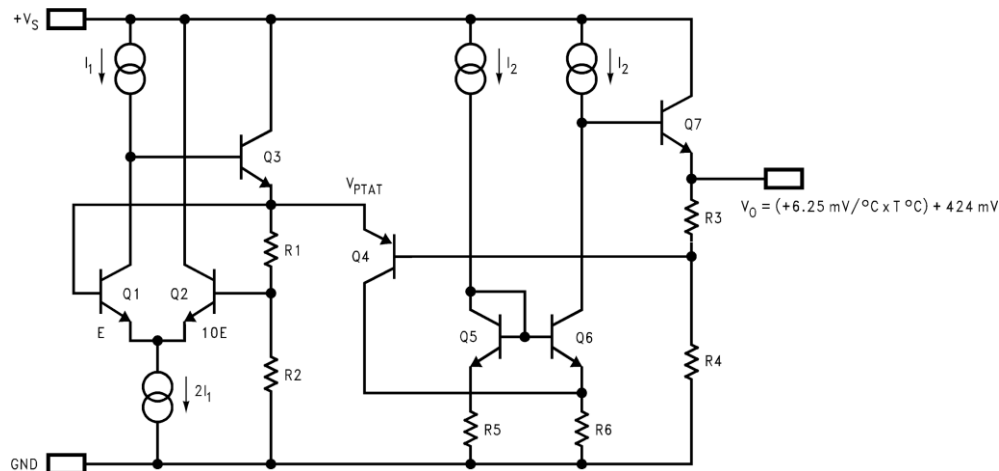
### 7.1 Overview

The LM60 device is a precision analog bipolar temperature sensor that can sense a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range while operating from a single 2.7V supply. The output voltage of the LM60 is linearly proportional to Celsius (Centigrade) temperature ( $6.25\text{mV}/^{\circ}\text{C}$ ) and has a DC offset of 424mV. The offset allows reading negative temperatures with a single positive supply. The nominal output voltage of the device ranges from 174mV to 1205mV for a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range. The device is calibrated to provide accuracies of  $\pm 2.0^{\circ}\text{C}$  at room temperature and  $\pm 3^{\circ}\text{C}$  over the full  $-25^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  (for Legacy chip) or  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  (for New chip) temperature range.

With a quiescent current of the device is less than  $110\mu\text{A}$  (for Legacy chip) and  $70\mu\text{A}$  (for New chip), self-heating is limited to a very low  $0.1^{\circ}\text{C}$  in still air in the SOT-23 package. Shutdown capability for the device is intrinsic because the inherent low power consumption allows the device to be powered directly from the output of many logic gates.

The output of the LM60 is a Class A base emitter follower, thus the LM60 can source quite a bit of current while sinking less than  $1\mu\text{A}$ . In any event load current must be minimized to limit the contribution to the total temperature error.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 LM60 Transfer Function

The LM60 follows a simple linear transfer function to achieve the accuracy as listed in [セクション 6.5](#) as given:

$$V_O = (6.25\text{mV}/^{\circ}\text{C} \times T^{\circ}\text{C}) + 424\text{mV} \quad (1)$$

where

- T is the temperature
- $V_O$  is the LM60 output voltage

### 7.4 Device Functional Modes

The only functional mode for this device is an analog output directly proportional to temperature.

## 8 Application and Implementation

### 注

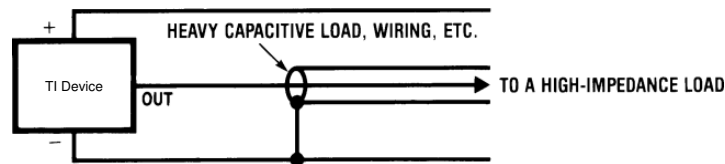
以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくこととなります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

### 8.1 Application Information

The device has a low supply current and a wide supply range, therefore it can easily be driven by a battery.

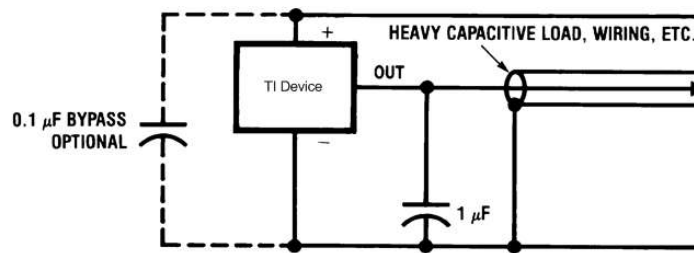
#### 8.1.1 Capacitive Loads

The device handles capacitive loading well. Without any special precautions, the device can drive any capacitive load as shown in 図 8-1. Over the specified temperature range the device has a maximum output impedance of  $800\Omega$ . In an extremely noisy environment, adding some filtering to minimize noise pick-up can be required. TI recommends that  $0.1\mu\text{F}$  be added from  $+V_S$  to GND to bypass the power supply voltage, as shown in 図 8-2. In a noisy environment, adding a capacitor from the output to ground can be required. A  $1\mu\text{F}$  output capacitor with the  $800\Omega$  output impedance forms a  $199\text{Hz}$ , low-pass filter. Because the thermal time constant of the device is much slower than the  $6.3\text{ms}$  time constant formed by the RC, the overall response time of the device is not be significantly affected. For much larger capacitors, this additional time lag increases the overall response time of the device.



Copyright © 2017, Texas Instruments Incorporated

図 8-1. No Decoupling Required for Capacitive Load



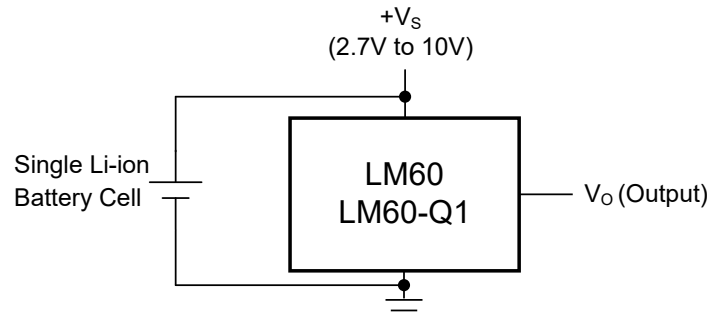
Copyright © 2017, Texas Instruments Incorporated

図 8-2. Filter Added for Noisy Environment

## 8.2 Typical Applications

### 8.2.1 Full-Range Centigrade Temperature Sensor

Because the LM60 is a simple temperature sensor that provides an analog output, design requirements related to the layout are also important. Refer to [セクション 8.5](#) for details.



$$V_O = (6.25\text{mV}/^\circ\text{C} \times T^\circ\text{C}) + 424\text{mV}$$

**図 8-3. Full-Range Centigrade Temperature Sensor (–40°C to +125°C) Operating From a Single Li-Ion Battery Cell**

#### 8.2.1.1 Design Requirements

For this design example, use the design parameters listed in [表 8-1](#).

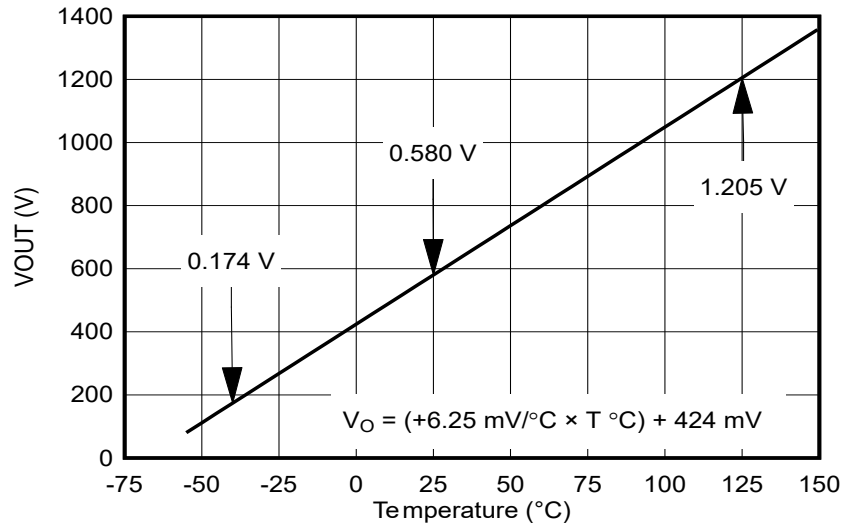
**表 8-1. Temperature and Typical V<sub>O</sub> Values of [図 8-3](#)**

TEMPERATURE (T)	TYPICAL V <sub>O</sub>
125°C	1205mV
100°C	1049mV
25°C	580mV
0°C	424mV
–25°C	268mV
–40°C	174mV

#### 8.2.1.2 Detailed Design Procedure

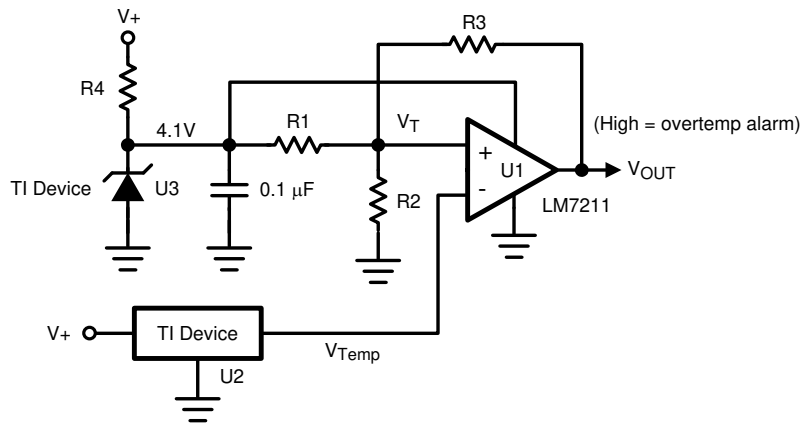
Selection of the LM60 is based on the output voltage transfer function being able to meet the needs of the rest of the system.

### 8.2.1.3 Application Curve



8-4. LM60 Output Transfer Function

### 8.2.2 Centigrade Thermostat Application



Copyright © 2017, Texas Instruments Incorporated

8-5. Centigrade Thermostat

#### 8.2.2.1 Design Requirements

A simple thermostat can be created by using a reference (LM4040) and a comparator (LM7211 or LMC7211-N) as shown in 8-5.

#### 8.2.2.2 Detailed Design Procedure

Use 式 2 and 式 3 to calculate the threshold values for T1 and T2.

$$V_{T1} = \frac{(4.1)R2}{R2 + R1 \parallel R3} \quad (2)$$

$$V_{T2} = \frac{(4.1)R2 \parallel R3}{R1 + R2 \parallel R3} \quad (3)$$

### 8.2.2.3 Application Curve

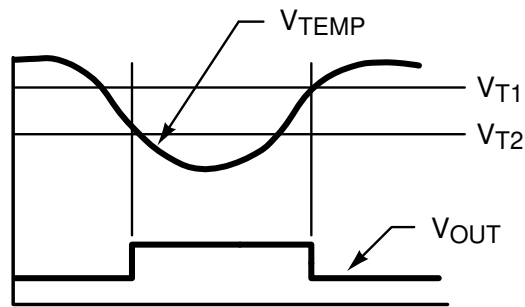
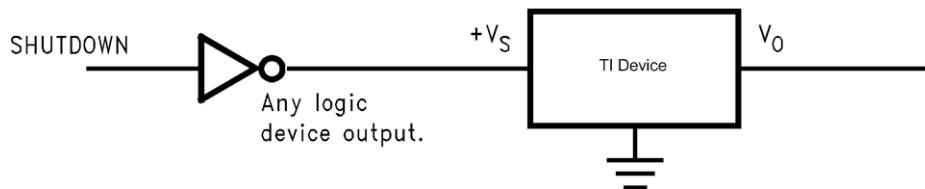


図 8-6. Thermostat Output Waveform

## 8.3 System Examples

### 8.3.1 Conserving Power Dissipation With Shutdown

The LM60 draws very little power, therefore the device can simply be shutdown by driving the LM60 supply pin with the output of a logic gate as shown in 図 8-7.



Copyright © 2017, Texas Instruments Incorporated

図 8-7. Conserving Power Dissipation With Shutdown

## 8.4 Power Supply Recommendations

In an extremely noisy environment, add some filtering to minimize noise pick-up. Adding 0.1µF from +V<sub>S</sub> to GND is recommended to bypass the power supply voltage, as shown in 図 8-2. In a noisy environment, add a capacitor from the output to ground.

## 8.5 Layout

### 8.5.1 Layout Guidelines

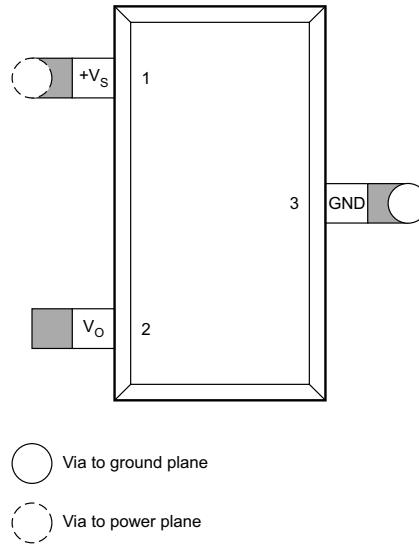
The LM60 can be applied easily in the same way as other integrated-circuit temperature sensors. The device can be glued or cemented to a surface. The temperature that the LM60 is sensing is within approximately +0.1°C of the surface temperature that the leads of the LM60 are attached to.

This presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature is much higher or lower than the surface temperature, the actual temperature of the device die is at an intermediate temperature between the surface temperature and the air temperature.

To provide good thermal conductivity, the backside of the device die is directly attached to the GND pin. The lands and traces to the device are part of the printed-circuit board, which is the object whose temperature is being measured. These printed-circuit board lands and traces do not cause the temperature of the device to deviate from the desired temperature.

Alternatively, the device can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the device and accompanying wiring and circuits must be kept insulated and dry to avoid leakage and corrosion. Specifically when the device operates at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to verify that moisture cannot corrode the device or connections.

### 8.5.2 Layout Example



1/2-inch square printed circuit board with 2-oz. copper foil or similar.

### 8-8. PCB Layout

### 8.5.3 Thermal Considerations

The thermal resistance junction to ambient ( $R_{\theta JA}$ ) is the parameter used to calculate the rise of a device junction temperature due to the device power dissipation. Use 式 4 to calculate the rise in the die temperature of the device.

$$T_J = T_A + R_{\theta JA} [(+V_S I_Q) + (+V_S - V_O) I_L] \quad (4)$$

where

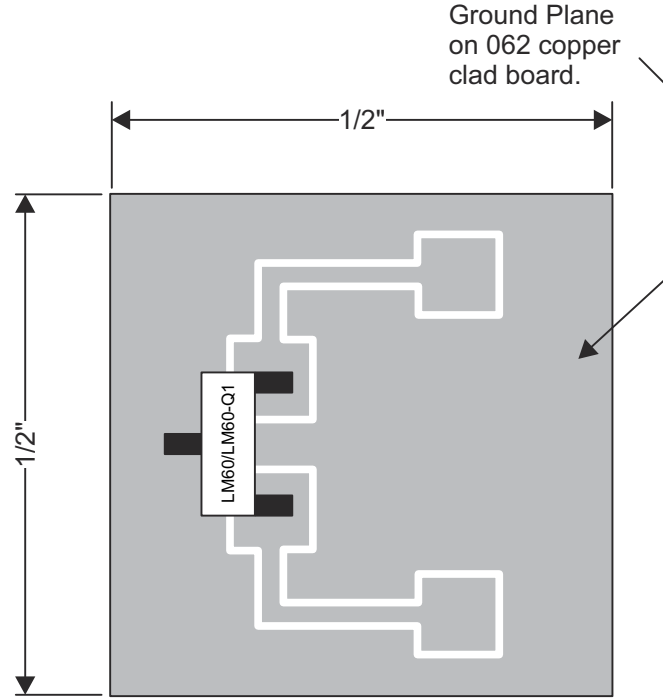
- $I_Q$  is the quiescent current
- $I_L$  is the load current on the output

表 8-2 summarizes the rise in die temperature of the LM60 without any loading, and the thermal resistance for different conditions. The values in 表 8-2 were actually measured where as the values shown in セクション 6.4 where calculated using modeling methods as described in the *Semiconductor and IC Package Thermal Metrics* (SPRA953) application report.

表 8-2. Temperature Rise of LM60 Due to Self-Heating and Thermal Resistance ( $R_{\theta JA}$ )

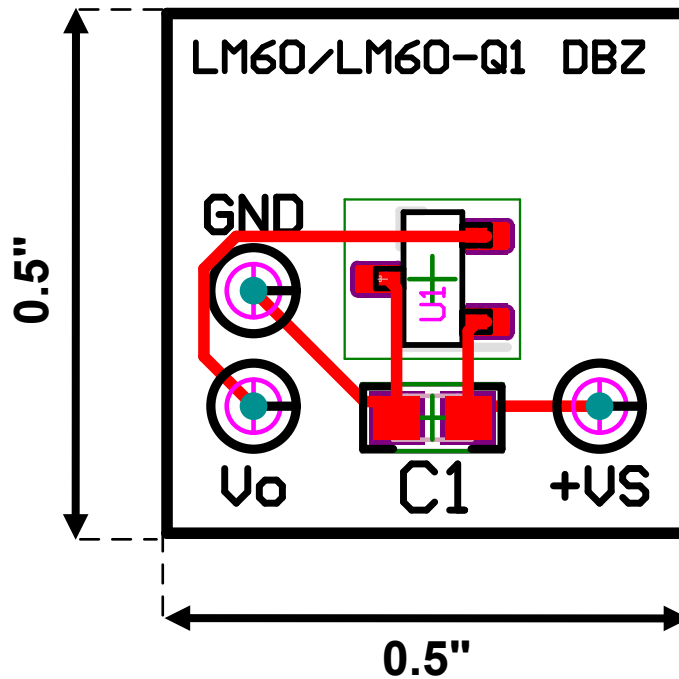
	SOT-23 <sup>(1)</sup> NO HEAT SINK		SOT-23 <sup>(2)</sup> SMALL HEAT FIN		TO-92 <sup>(1)</sup> NO HEAT FIN		TO-92 <sup>(3)</sup> SMALL HEAT FIN	
	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$
	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)
Still air Legacy chip	450	0.17	260	0.1	180	0.07	140	0.05
Moving air Legacy chip	—	—	180	0.07	90	0.034	70	0.026

- (1) Part soldered to 30 gauge wire.
- (2) Heat sink used is 1/2-in square printed-circuit board with 2-oz. foil with part attached as shown in 8-9.
- (3) Part glued or leads soldered to 1-in square of 1/16-in printed-circuit board with 2-oz. foil or similar.



1/2-in Square Printed-Circuit Board with 2oz. Copper Foil or Similar.

8-9. Printed-Circuit Board Used for Heat Sink to Generate Thermal Response Curves (Legacy chip)



1/2in Square Printed-Circuit Board with FR-4 material.

8-10. Printed-Circuit Board Used to Generate Thermal Response Curves (New Test Setup for Both New Chip and Legacy Chip)



## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [LM50 and LM50-Q1 SOT-23 Single-Supply Centigrade Temperature Sensor](#), data sheet
- Texas Instruments, [TMP23x Low-Power, High-Accuracy Analog Output Temperature Sensors](#), data sheet
- Texas Instruments, [LM60 Evaluation Module](#), EVM user's guide
- Texas Instruments, [LM60-Q1 Functional Safety FIT Rate and FMD](#), Functional safety information.

### 9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[www.tij.co.jp](http://www.tij.co.jp) のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

### 9.3 サポート・リソース

[テキサス・インスツルメンツ E2E™ サポート・フォーラム](#)は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの[使用条件](#)を参照してください。

### 9.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.  
すべての商標は、それぞれの所有者に帰属します。

### 9.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

### 9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

## 10 Revision History

### Changes from Revision F (August 2017) to Revision G (February 2025)

Page

• ドキュメント全体にわたって表、図、相互参照の採番方法を更新.....	1
• Updated the <i>Device Comparison</i> section with existing OPNs and adding <i>Device Nomenclature</i> table.....	3
• Changed Machine model (MM) Electrostatic discharge to Charged-device model (CDM).....	4
• Changed minimum specified temperature for LM60B from -25°C to -40°C in the New chip.....	4
• Changed DBZ and LP packages Thermal Information section. in the New chip.....	4
• Added “operating current” and “Change of quiescent current” for the New chip.....	5
• Added graphs for new chip, reordered and corrected the graphs for legacy chip.....	6
• Added corrections to the <i>Thermal Resistance Junction to Air (Legacy chip)</i> graph.....	6
• Added <i>Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches × 0.5 inches PCB board)</i> graph for both Legacy and New chips.....	6

- Added *Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip together in a new test setup)* graph for both Legacy and New chips.....6
- Added the *Start-Up Voltage vs Temperature, Quiescent Current vs Temperature, Accuracy vs Temperature, Noise Voltage, Supply Current vs Supply Voltage* and *Start-Up Response* graphs for New chip.....6

#### Changes from Revision E (September 2015) to Revision F (August 2017) Page

- 車載用デバイスをスタンドアロンのデータシート (SNIS197) へ移動..... 1
- Added table note for the LM60B.....3

#### Changes from Revision D (November 2012) to Revision E (November 2014) Page

- 「ピン構成および機能」セクション、「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加 ..... 1

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## 重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した テキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている テキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的のみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかる テキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2025, Texas Instruments Incorporated

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM60BIM3	NRND	Production	SOT-23 (DBZ)   3	1000   SMALL T&R	No	Call TI	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3.Z	NRND	Production	SOT-23 (DBZ)   3	1000   SMALL T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6B
<a href="#">LM60BIM3/NOPB</a>	Obsolete	Production	SOT-23 (DBZ)   3	-	-	Call TI	Call TI	-25 to 125	T6B
LM60BIM3X	NRND	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	No	Call TI	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X.Z	NRND	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6B
<a href="#">LM60BIM3X/NOPB</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X/NOPB.Z	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	T6B
<a href="#">LM60BIZ/LFT3</a>	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/LFT3.Z	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60BIZ) BIZ
<a href="#">LM60BIZ/NOPB</a>	Active	Production	TO-92 (LP)   3	1800   SMALL T&R	-	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/NOPB.Z	Active	Production	TO-92 (LP)   3	1800   SMALL T&R	-	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60BIZ) BIZ
LM60CIM3	NRND	Production	SOT-23 (DBZ)   3	1000   SMALL T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3.Z	NRND	Production	SOT-23 (DBZ)   3	1000   SMALL T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C
<a href="#">LM60CIM3/NOPB</a>	Obsolete	Production	SOT-23 (DBZ)   3	-	-	Call TI	Call TI	-40 to 125	T6C
LM60CIM3X	NRND	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X.Z	NRND	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	No	Call TI	Level-1-260C-UNLIM	-40 to 125	T6C
<a href="#">LM60CIM3X/NOPB</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X/NOPB.Z	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	T6C
<a href="#">LM60CIZ/NOPB</a>	Active	Production	TO-92 (LP)   3	1800   SMALL T&R	-	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60CIZ) CIZ
LM60CIZ/NOPB.Z	Active	Production	TO-92 (LP)   3	1800   SMALL T&R	-	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60CIZ) CIZ

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF LM60 :

- Automotive : [LM60-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM60BIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60BIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM60BIM3	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM60BIM3X	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60CIM3	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM60CIM3X	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0

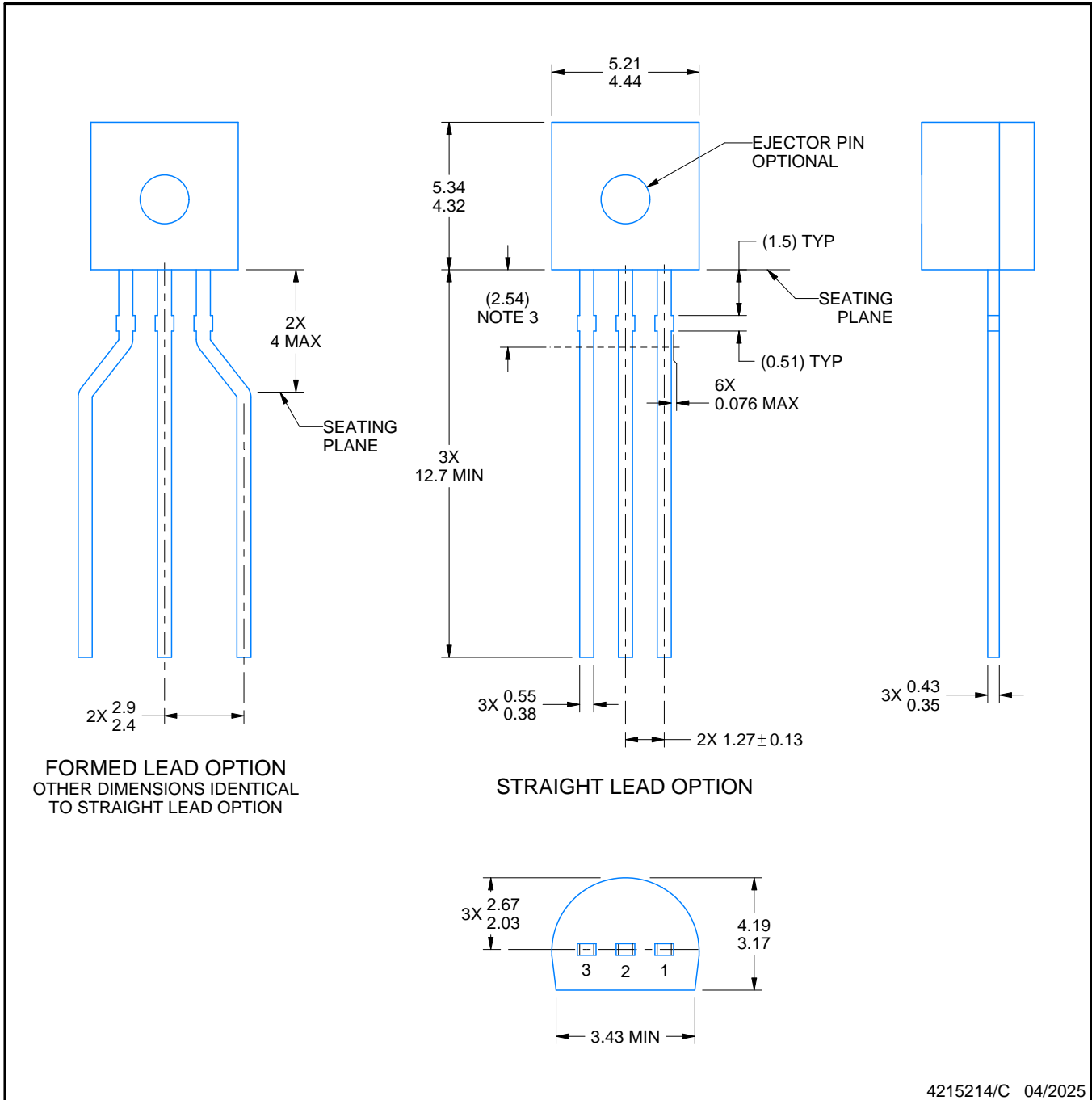
LP0003A



# PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



4215214/C 04/2025

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
  - a. Straight lead option available in bulk pack only.
  - b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.

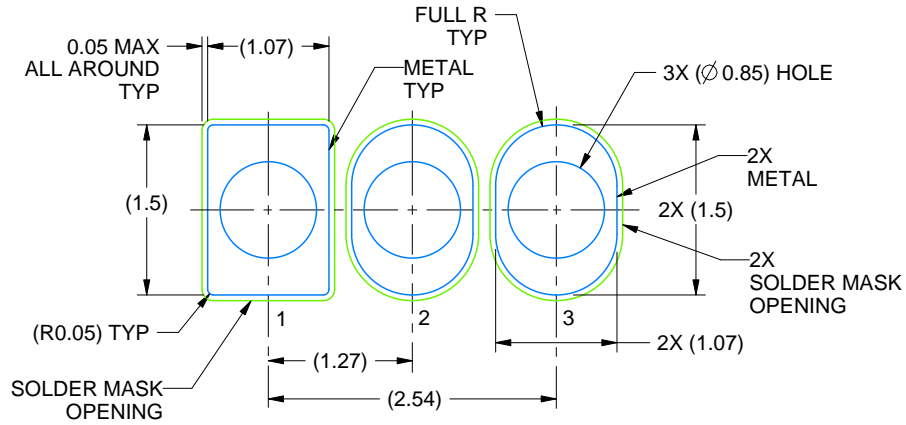


# EXAMPLE BOARD LAYOUT

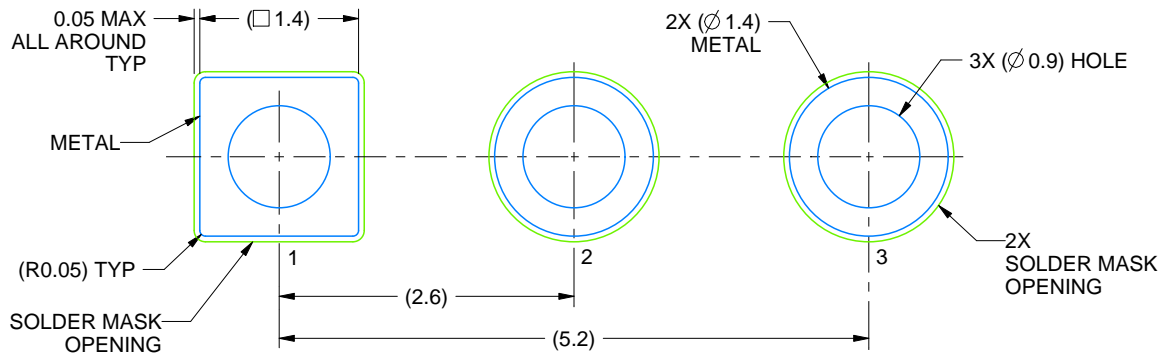
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE  
STRAIGHT LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X



LAND PATTERN EXAMPLE  
FORMED LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X

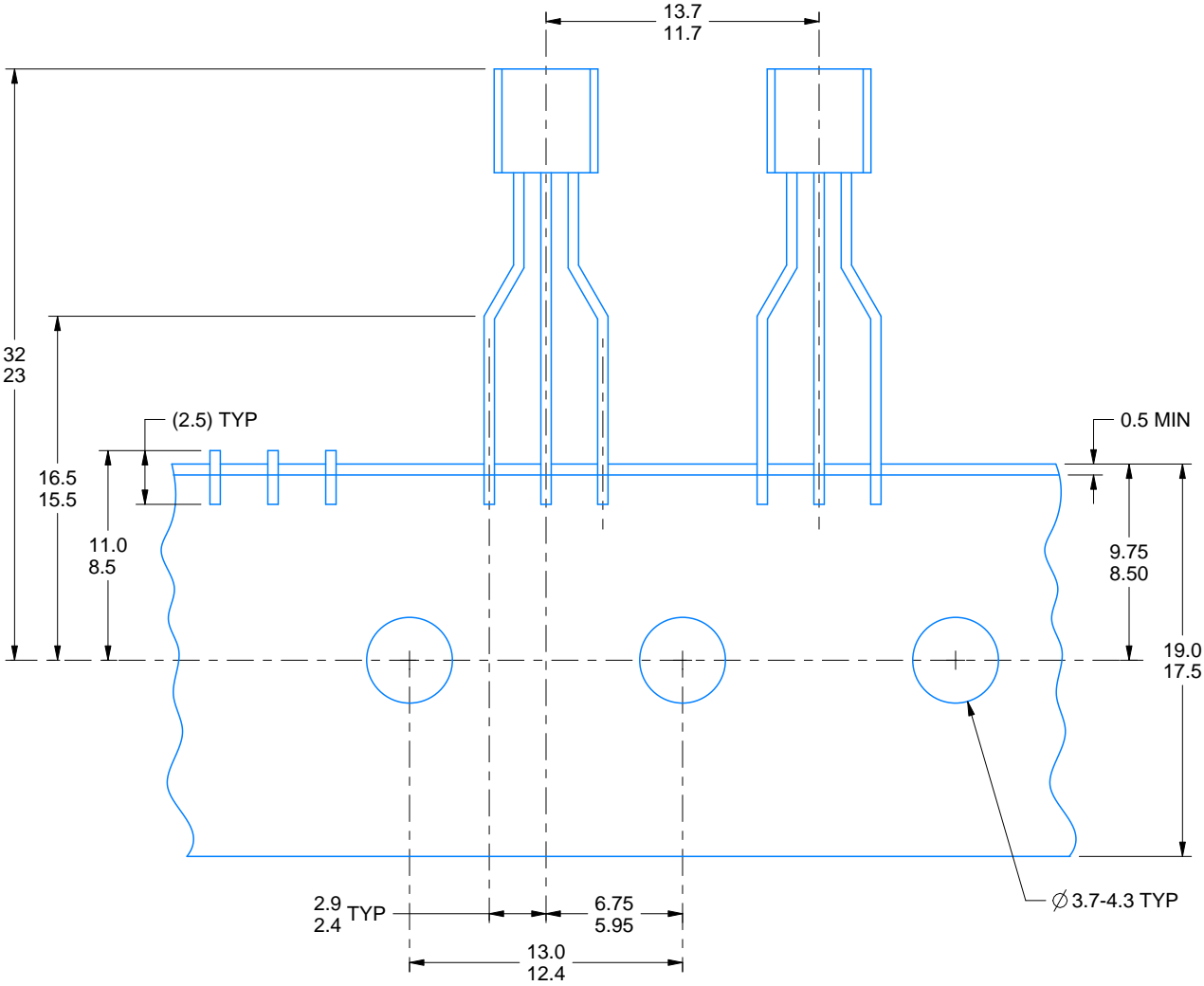
4215214/C 04/2025

**TAPE SPECIFICATIONS**

**LP0003A**

**TO-92 - 5.34 mm max height**

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/C 04/2025

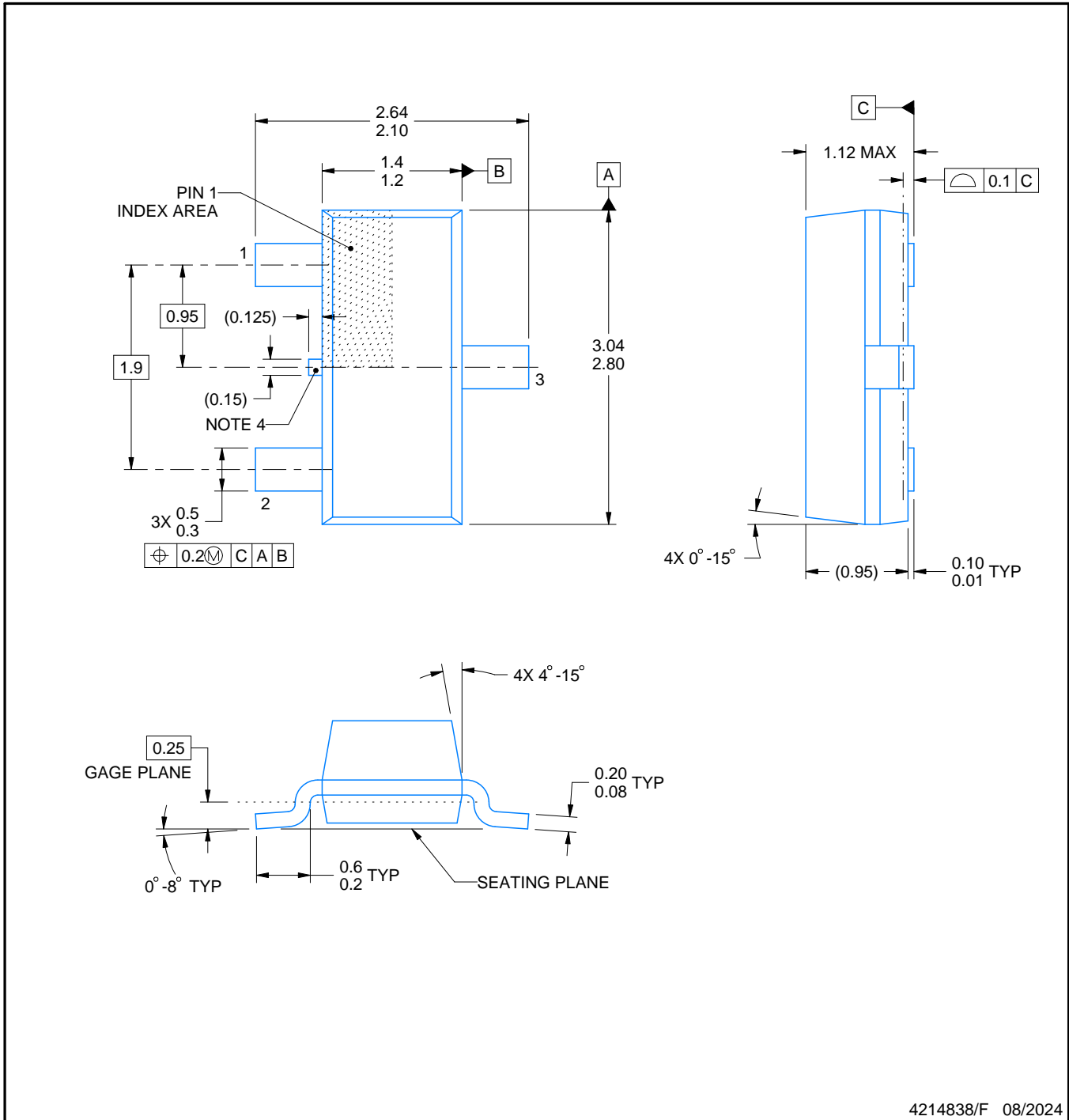
DBZ0003A



# PACKAGE OUTLINE

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



4214838/F 08/2024

NOTES:

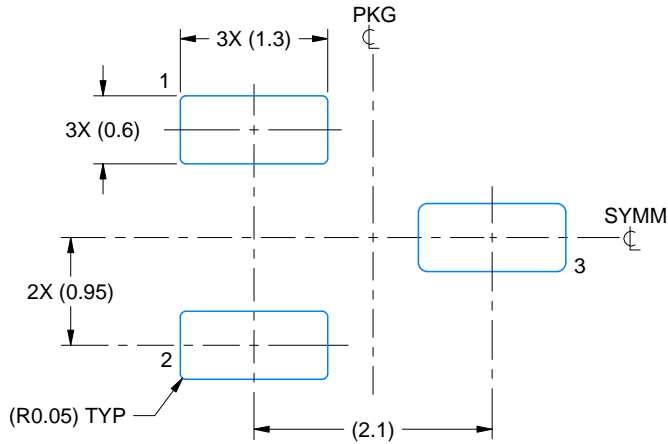
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
4. Support pin may differ or may not be present.
5. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

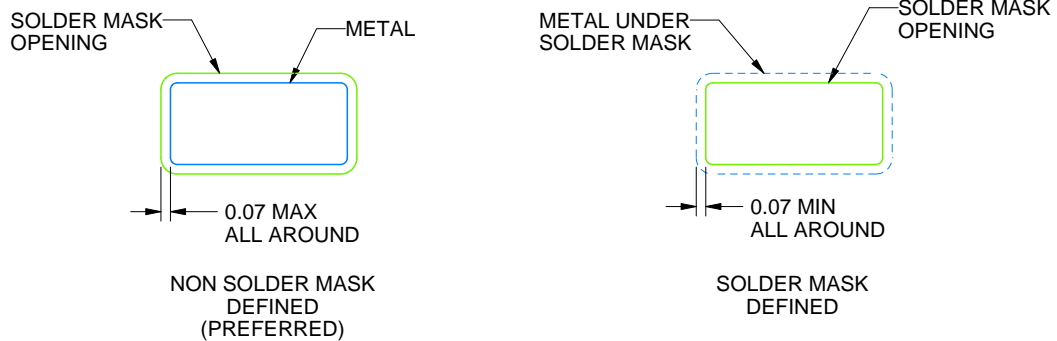
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
SCALE:15X



SOLDER MASK DETAILS

4214838/F 08/2024

NOTES: (continued)

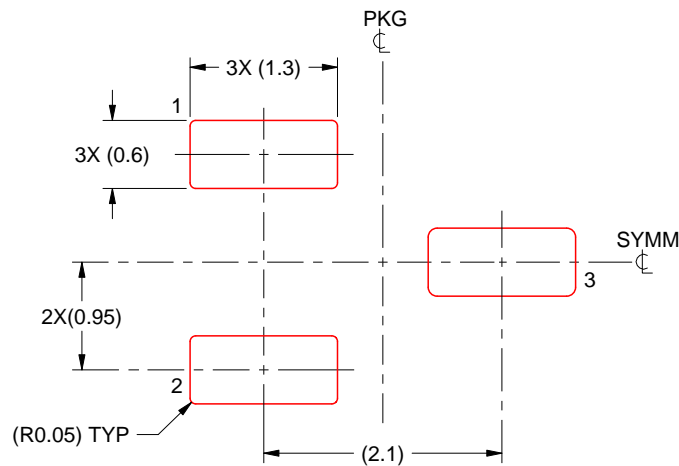
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:15X

4214838/F 08/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## 重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ(データシートを含みます)、設計リソース(リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適したテキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されているテキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかるテキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2025, Texas Instruments Incorporated